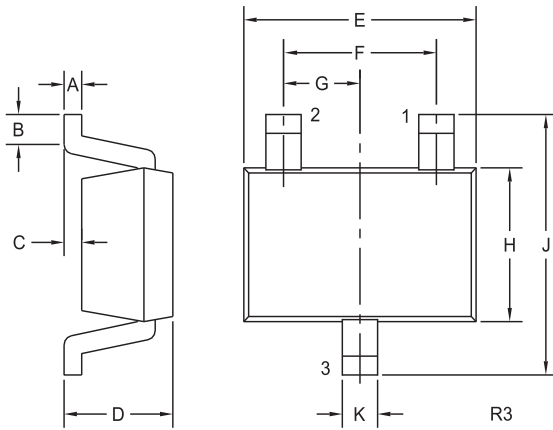


# Package Details

## SOT-323 Case



### Mechanical Drawing



SYMBOL	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.002	0.008	0.05	0.20
B	0.004	-	0.10	-
C	-	0.004	-	0.10
D	0.031	0.043	0.80	1.10
E	0.071	0.087	1.80	2.20
F	0.051		1.30	
G	0.026		0.65	
H	0.045	0.053	1.15	1.35
J	0.079	0.087	2.00	2.20
K	0.008	0.016	0.20	0.40

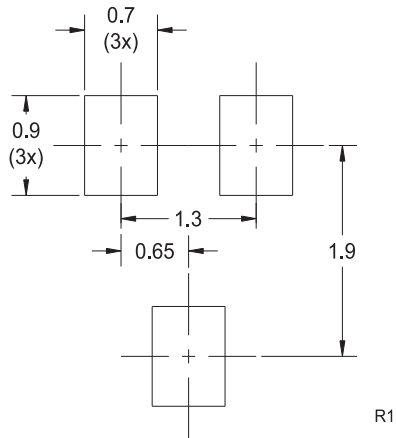
SOT-323 (REV: R3)

#### Lead Code:

Reference individual device datasheet.

#### Part Marking: 2-3 Character Alpha/Numeric Code

### Mounting Pad Geometry (Dimensions in mm)



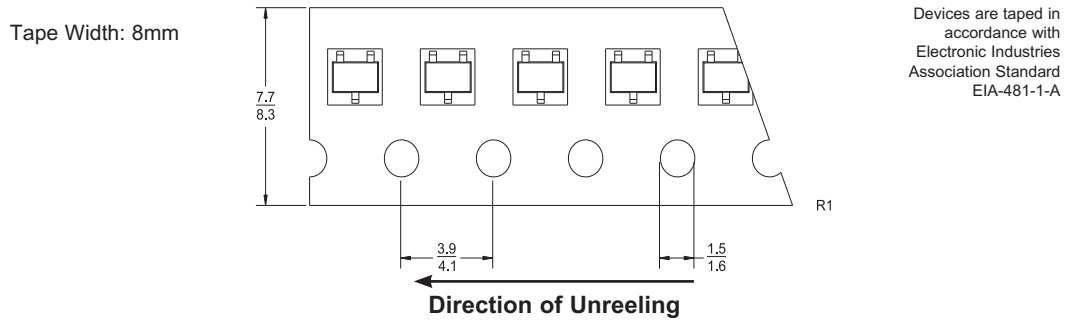
R4 (4-March 2010)

# Package Details

## SOT-323 Case



### Tape Dimensions and Orientation (Dimensions in mm)



### Packaging Base

7" Reel = 3,000 pcs.

### Reel Labeling Information

**Each reel is labeled with the following information:**  
 Central Part Number, Customer Part Number, Purchase Order Number,  
 Quantity, Lot Number, Date Code, Ship Date and Marking Code.

### Reel Packing Information

Reel Size	Reels per Box (Maximum)	Parts per Box (Maximum)	Box Dimensions		Shipping Weight (Max.)	
			INCH	CM	LB	KG
7"	9	27,000	9x9x5	23x23x13	3	2
	18	54,000	9x9x9	23x23x23	6	3
	40	120,000	21x9x9	53x23x23	13	6
	108	324,000	27x9x17	69x23x43	34	16

### Ordering Information

- For devices taped and reeled on 7" reels, add TR suffix to part number.
- All SMDs are available in small quantities for prototype and manual placement applications.

R4 (4-March 2010)

# Material Composition Specification

## SOT-323 Case



Device average mass . . . . . **5.47 mg**  
 Fluctuation margin . . . . . **+/-10%**

Component	Material	Material		Substance	CAS No.	Substance		
		(%wt)	(mg)			(%wt)	(mg)	(ppm)
active device	doped Si	4.2%	0.23	Si	7440-21-3	4.2%	0.23	42,048
bond wire	gold or copper	0.37%	0.02	Au	7440-57-5	0.37%	0.02	3,656
				Cu	7440-50-8			
leadframe	alloy 42 w/ silver plating	23.77%	1.3	Fe	7439-89-6	13.71%	0.75	137,112
				Ni	7440-02-0	9.51%	0.52	95,064
				Ag	7440-22-4	0.55%	0.03	5,484
encapsulation*	EMC	67.46%	3.69	silica	7631-86-9	49.91%	2.73	499,086
				epoxy resin	Proprietary	15.72%	0.86	157,221
				Sb <sub>2</sub> O <sub>3</sub>	1309-64-4	1.28%	0.07	12,797
				Br	7726-95-6	0.37%	0.02	3,656
				carbon	1333-86-4	0.18%	0.01	1,828
	EMC GREEN	67.46%	3.69	silica (fused)	60676-86-0	51.94%	2.841	519,442
				epoxy resin	29690-82-2	6.75%	0.369	67,456
				phenol resin	9003-35-4	6.54%	0.358	65,433
				carbon black	1333-86-4	0.2%	0.011	2,023
				metal hydroxide	1309-42-8	2.02%	0.111	20,235
plating**	tin/lead process	4.2%	0.23	Sn	7440-31-5	3.29%	0.18	32,907
				Pb	7439-92-1	0.91%	0.05	9,141
	matte tin	4.2%	0.23	Sn	7440-31-5	4.2%	0.23	42,048

\*EMC GREEN molding compound is Halogen-Free.

\*\*For Lead Free plating, add suffix "PB FREE" to part number.

For Tin/Lead plating, add suffix "TIN/LEAD" to part number.

No suffix designation allows for the supply of either lead-free or tin/lead plated product depending on availability.

### Disclaimer

The information provided in this Material Composition data sheet is, to the best of our knowledge, correct. However, there is no guarantee to completeness or accuracy, as some information is derived from data sources outside the company.

R8 (16-July 2018)